

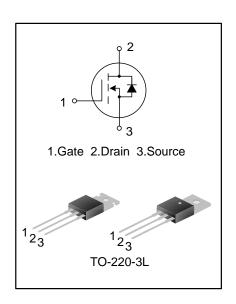
# 110A, 55V, N-Channel MOSFET

### **General Description**

GGVD3205T is an N-channel enhancement mode power MOS field effect transistor. The improved planar stripe cell and the improved guard ring terminal have been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulses in the avalanche and commutation mode.

#### **Features**

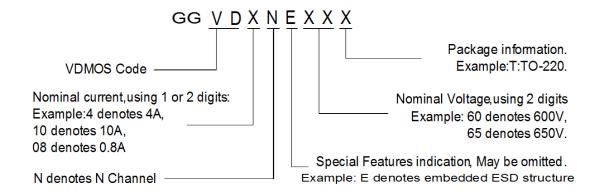
- 110A, 55V
- $R_{DS(on)} (typ) = 7.5 \text{m}\Omega@V_{GS} = 10V$
- Low gate charge
- Low Crss
- Fast switching
- Improved dv/dt capability



### **Applications**

- AC-DC power supplies
- DC-DC converters
- H-bridge PWM motor drivers

#### **Nomenclature**



## **Ordering Information**

Part No.	Package	Marking	Material	Packing	
GGVD3205T	TO-220-3L	GGVD3205T	Pb free	Tube	



# **Absolute Maximum Ratings** (T<sub>C</sub>=25°C unless otherwise noted)

Characteristics		Symbol	Rating	Unit	
Drain-Source Voltage		$V_{DS}$	55	V	
Gate-Source Voltage		$V_{GS}$	±20	V	
Drain Current	T <sub>C</sub> =25°C	I <sub>D</sub>	110	А	
	T <sub>C</sub> =100°C		80		
Drain Current Pulsed		I <sub>DM</sub>	390	Α	
Power Dissipation(T <sub>C</sub> =25°C)			200	W	
-Derate above 25°C		$P_{D}$	1.3	W/°C	
Single Pulsed Avalanche Energy(Note 1)		E <sub>AS</sub>	1050	mJ	
Operation Junction Temperature Range		T <sub>J</sub>	<b>-</b> 55∼ <b>+</b> 150	°C	
Storage Temperature Range		T <sub>stg</sub>	<b>-55∼+150</b>	°C	

### **Thermal Characteristics**

Characteristics	Symbol	Rating	Unit
Thermal Resistance, Junction-to-Case	$R_{ heta JC}$	0.75	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62	°C/W

# **Electrical Characteristics** (T<sub>C</sub>=25°C unless otherwise noted)

Characteristics	Symbol	Test conditions	Min.	Тур.	Max.	Unit
Drain -Source Breakdown Voltage	B <sub>VDSS</sub>	$V_{GS}$ =0V, $I_D$ =250 $\mu$ A	55			V
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =55V, V <sub>GS</sub> =0V			25	μΑ
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm20V, V_{DS}=0V$			±100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS} = V_{DS}$ , $I_D = 250 \mu A$	2.8		4.8	V
Static Drain- Source On State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =55A	1	7.5	8.0	mΩ
Input Capacitance	C <sub>iss</sub>	N 05)/ N 0)/		3247		
Output Capacitance	C <sub>oss</sub>	$V_{DS}=25V$ , $V_{GS}=0V$ ,		781		pF
Reverse Transfer Capacitance	$C_{rss}$	f=1.0MHz		211		
Turn-on Delay Time	$t_{d(on)}$			14		
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}$ =28V, $V_{GS}$ =25V, $R_{G}$ =50 $\Omega$	-	101		
Turn-off Delay Time	$t_{d(off)}$			50		ns
Turn-off Fall Time	t <sub>f</sub>			65		
Total Gate Charge	$Q_g$				146	
Gate-Source Charge	$Q_gs$	V <sub>DS</sub> =44V, I <sub>D</sub> =62A, V <sub>GS</sub> =10V			35	nC
Gate-Drain Charge	$Q_gd$				54	



## **Source-Drain Diode Ratings and Characteristics**

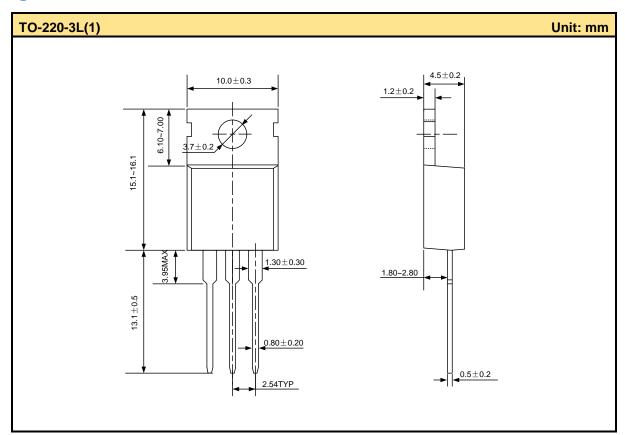
Characteristics	Symbol	Test conditions	Min.	Тур.	Max.	Unit
Continuous Source Current	I <sub>S</sub>	Integral Reverse P-N			110	
Pulsed Source Current	I <sub>SM</sub>	Junction Diode in the MOSFET			390	Α
Diode Forward Voltage	$V_{SD}$	I <sub>S</sub> =110A, V <sub>GS</sub> =0V			1.3	V
Reverse Recovery Time	T <sub>rr</sub>	I <sub>S</sub> =110A, V <sub>GS</sub> =0V,		69	104	ns
Reverse Recovery Charge	$Q_{rr}$	dI <sub>F</sub> /dt=100A/μs		143	215	μC

#### Notes:

- 1. L=138 $\mu$ H, I<sub>AS</sub>=110A, V<sub>DD</sub>=25V, R<sub>G</sub>=0 $\Omega$ , starting T<sub>J</sub>=25°C;
- 2. Pulse Test: Pulse width ≤300µs, Duty cycle≤2%;
- 3. Essentially independent of operating temperature.

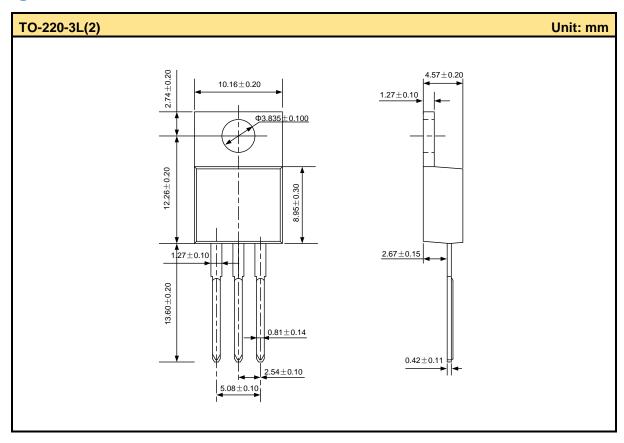


# **Package Outline**





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